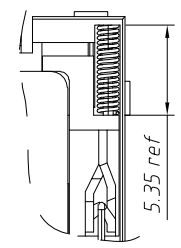
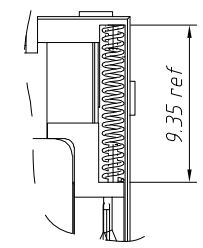
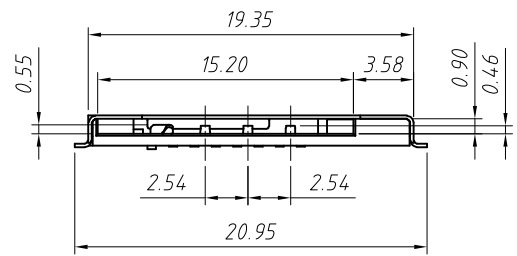


Pin No.	DESCRIPTION
P1#	C1:VCC
P2#	C5:GND
P3#	C2:RST
P4#	C6:VPP
P5#	C3:CLK
P6#	C7:I/O
P7#	POL
P8#	DET

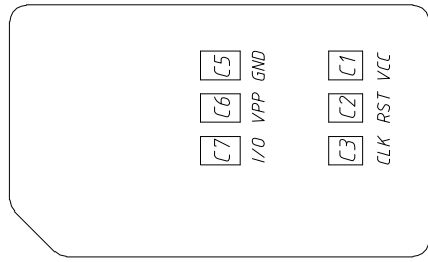
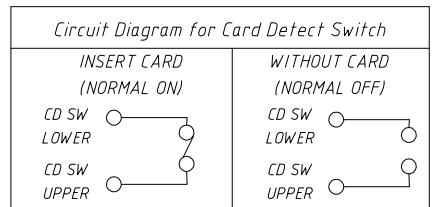


Preloading state

Working condition

RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ±0.05

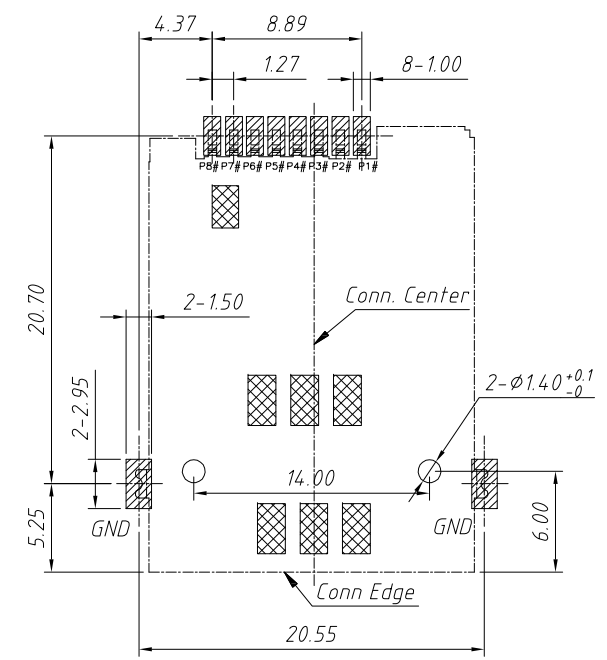
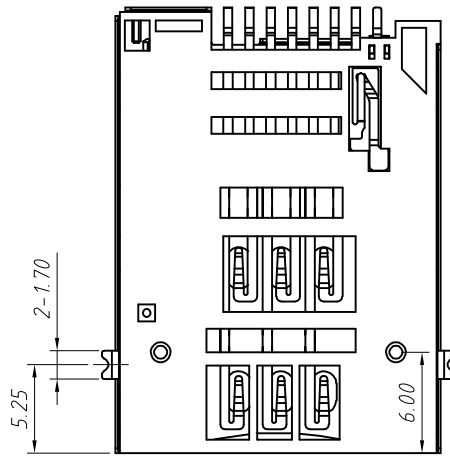
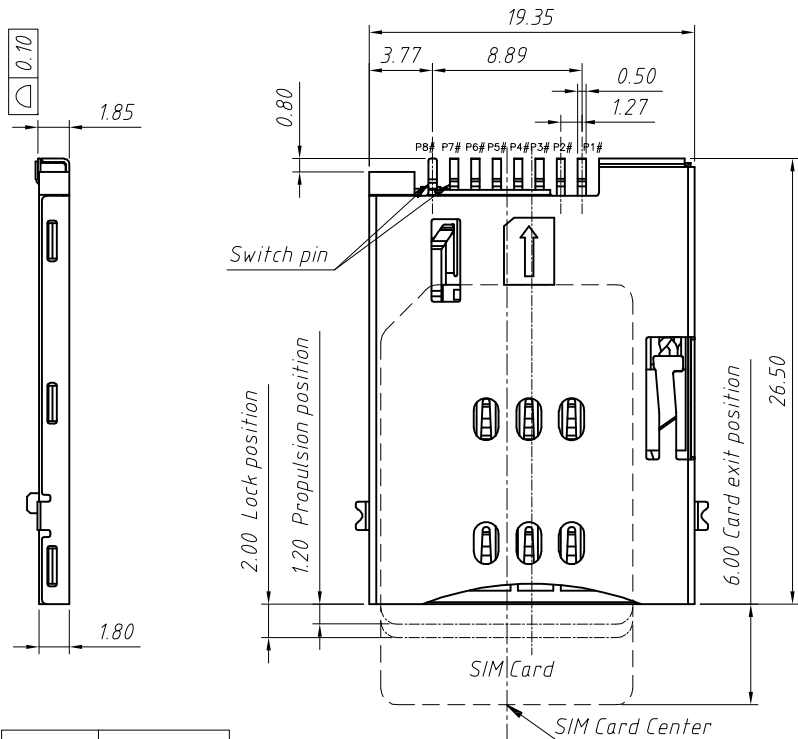
SOLDER AREA
 NONE CIRCUIT DIAGRAM AREA



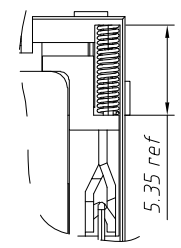
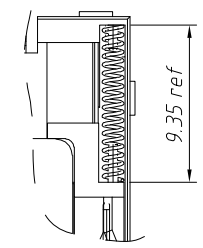
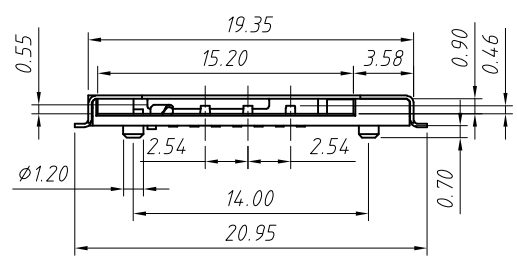
SIM diagram
Chip face down view

Material:
Insulator: High Temperature Thermoplastic
Contact: Copper Alloy
Shell: Steel
Finish:
Contact: Gold Flash Plated on Contact Area;
Matte-Tin Plated on Solder Tails;
With Entire Contact Underplated Nickel.
Shell: Gold Flash Plated on Solder Tails.
Infrared Reflow Soldering: 10 sec. Min. at 260⁺¹⁰/₋₀

GENERAL TOLERANCE	PROJECTION		Description:
.X ±0.50	UNITS	mm	SIM card connectors 6+2 pin Push H1.8 (Without Post)
.X ±0.25	SCALE	2:1	
.XX ±0.10	Draw by:	Jenny	KLS P/N: L-KLS1-SIM-110-6P-0-R
ANGLE TOLERANCE	Check by:		NingBo KLS ELECTRONIC CO.,L TD.
.X ±5°	Date	2018-03-01	
.X ±3°	SHEET	1 OF 1	



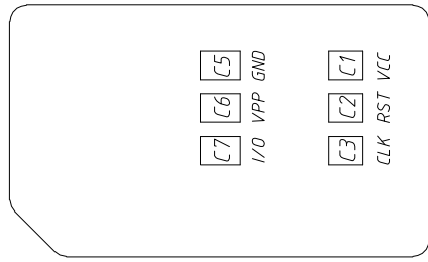
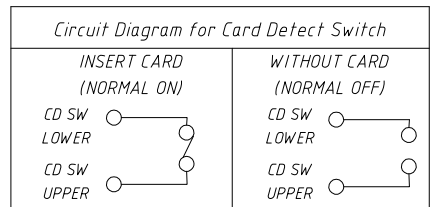
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Preloading state Working condition

RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ±0.05

- SOLDER AREA
- NONE CIRCUIT DIAGRAM AREA



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.X ±0.25	SCALE	2:1	
.XX ±0.10	Draw by:	Jenny	
ANGLE TOLERANCE	Check by:		KLS P/N: L-KLS1-SIM-110-6P-1-R
.X ±5°	Date	2018-03-01	NingBo KLS ELECTRONIC CO.,L TD.
.X ±3°	SHEET	1 OF 1	
.XX ±2°			